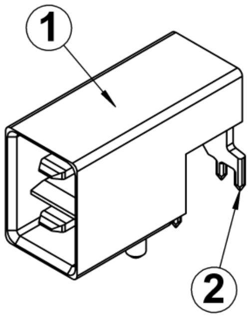
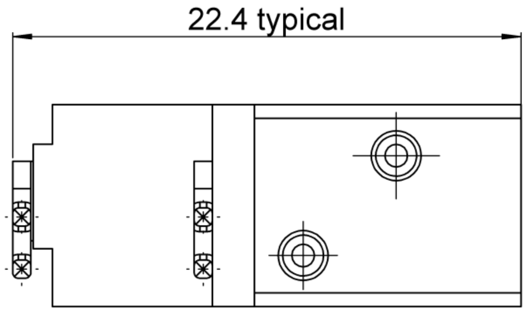
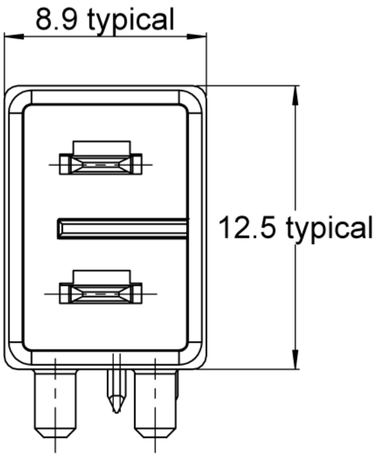
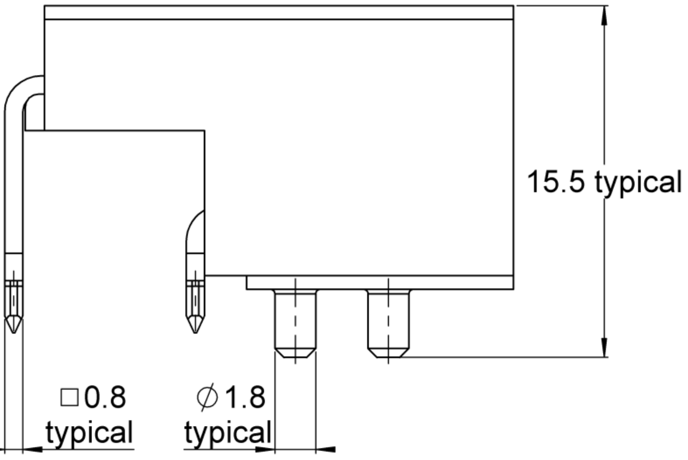
PAGE **1/5**	ISSUE **30-07-24A**	SERIES **OCTIS**	PART NUMBER **OCTI360500**









All dimensions are 8in mm. Unmarked tolerance is ±0.3mm

DESCRIPTION

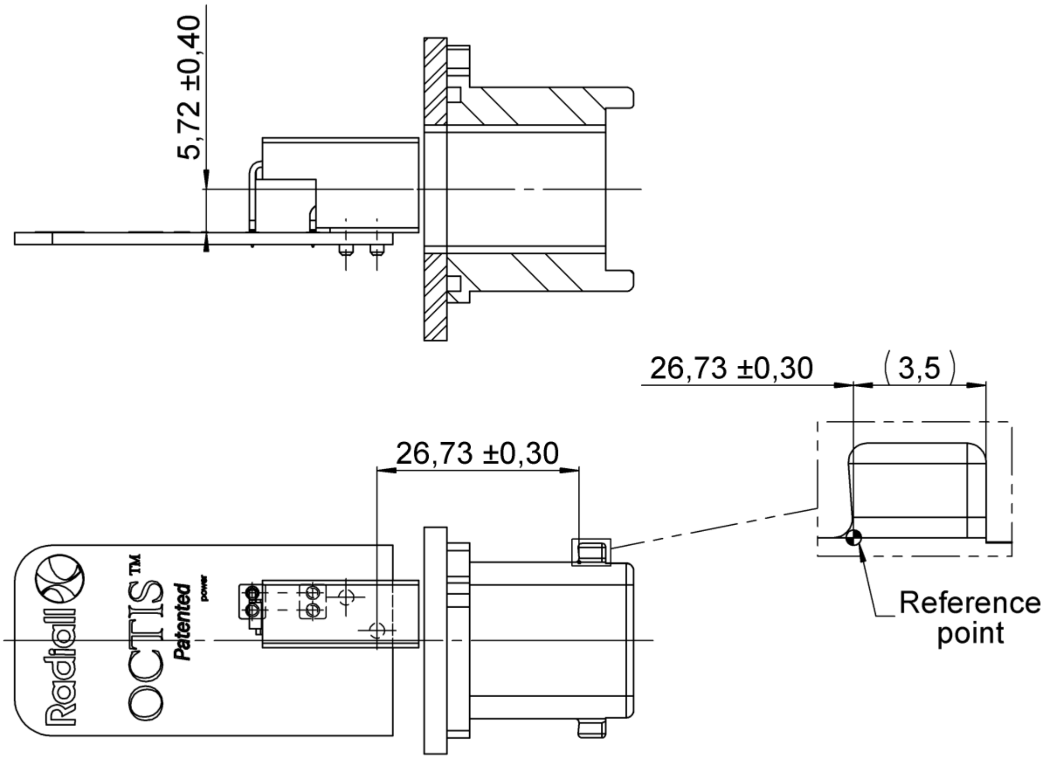
REP	COMPONENT	MATERIALS	PLATING
1	**Housing**	**PLASTIC**	**-**
2	**Contact**	**COPPER ALLOY**	**SN**

GENERAL CHARACTERISTICS

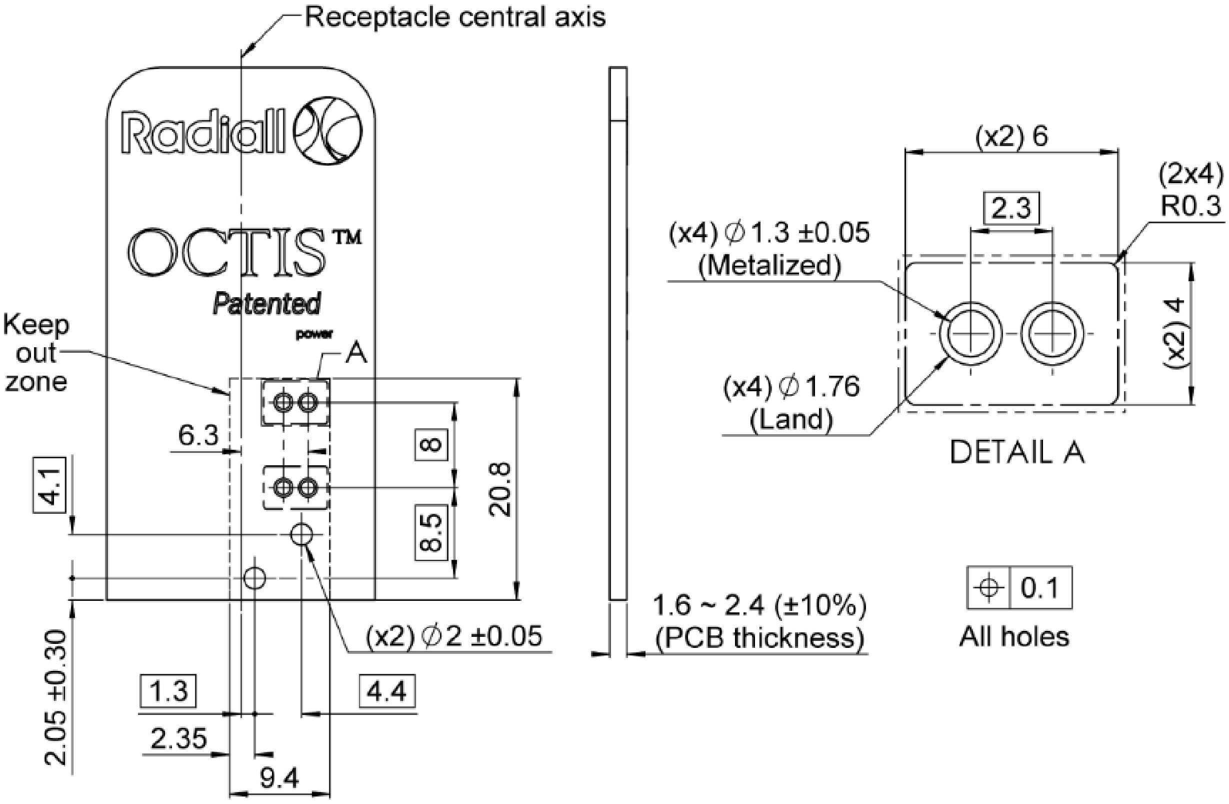
Mechanical		
Mating endurance (cycles)	EIA 364-09	100
Vibration	IEC 60068-2-6	10-150-10 Hz
Weight (g)	-	2.573
Environmental		
Operating temperature (°C)	-	-40 / +105
Storage temperature (°C)	-	-65 / +105
RoHS	-	Compliant
Flammability	UL 94	V0
Electrical		
Working voltage	-	Max. 300V DC (r.m.s.)
Current rating	-	30A per contact
Dielectric withstanding voltage	EIA 364-20	500V DC
Insulation resistance	EIA 364-21	5000MΩ minimum initial 1000MΩ minimum after environmental aging
Others		
OCTIS Plug	-	For use with OCTI3175xx or OCTI3275xx
Packaging	-	Packaging in Tape & Reel, 185 per reel.

(*) Mated condition

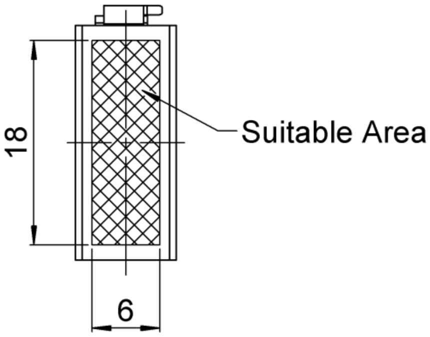
POSITIONING AND PATTERN DEFINITION



FOOT/PRINT (General tolerance for PCB ±0.1 mm)



SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



SOLDER PROCEDURE*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.

2. Place the component on the mounting area with a pick & place machine.
   A video camera is recommended for a good positioning of the component.
   Adhesive agents must not be used on the component.

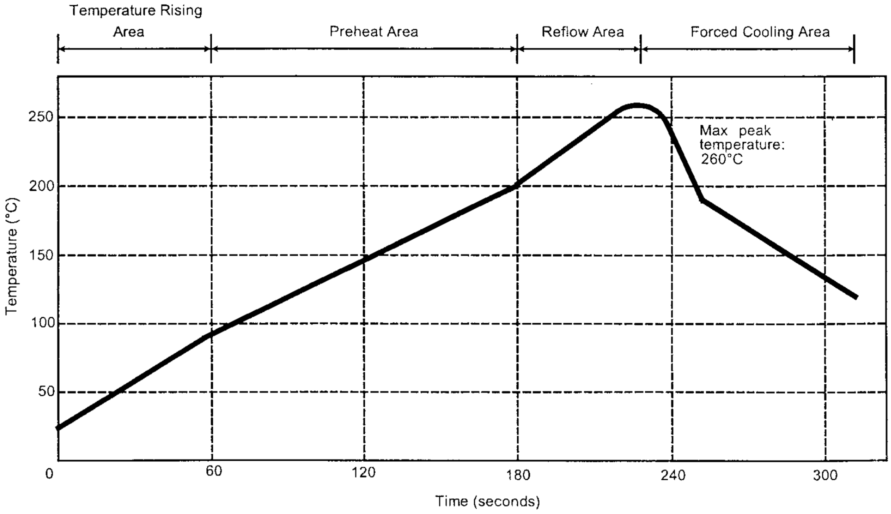
3. This process of soldering has been tested with a convection oven.
   Below please find the typical soldering profile to use.

4. Optional cleaning of printed circuit board.

5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

* Typical data for reflow process. Alternatively, wave soldering is also possible